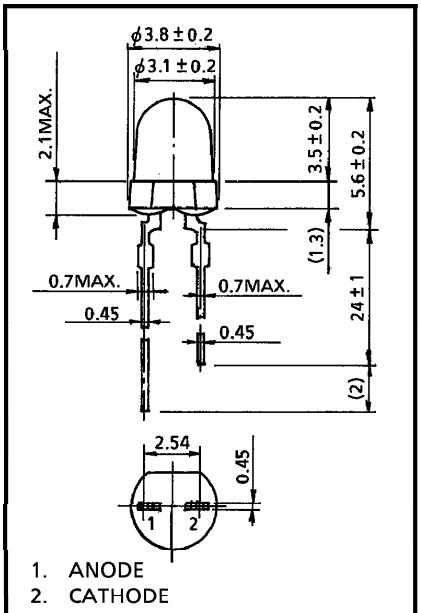
TOSHIBA LED LAMP InGaAℓP GREEN LIGHT EMISSION

TLGE123

PANEL CIRCUIT INDICATOR

Unit in mm

- 3 mm DIAMETER (T1-3 / 4)
- InGaAℓP GREEN LED
- All Plastic Mold Type.
- Colored Transparent Lens
- Low Drive Current, High Intensity Green Light Emission
  Recommended Forward Current : I_F = 15~20 mA (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.



JEDEC	—
EIAJ	—
TOSHIBA	4-4E1A

Weight : 0.14 g

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I_F	50	mA
Reverse Voltage	V_R	4	V
Power Dissipation	P_D	140	mW
Operating Temperature Range	T_{opr}	−30~85	°C
Storage Temperature Range	T_{stg}	−40~120	°C

ELECTRICAL AND OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Forward Voltage	V_F	I_F = 20 mA	—	2.27	2.8	V
Reverse Current	I_R	V_R = 4 V	—	—	50	μA
Luminous Intensity	I_V	I_F = 20 mA (Note)	(153)	450	—	mcd
Peak Emission Wavelength	λ_p	I_F = 20 mA	—	574	—	nm
Spectral Line Half Width	$\Delta\lambda$	I_F = 20 mA	—	14	—	nm
Dominant Wavelength	λ_d	I_F = 20 mA	—	571	—	nm

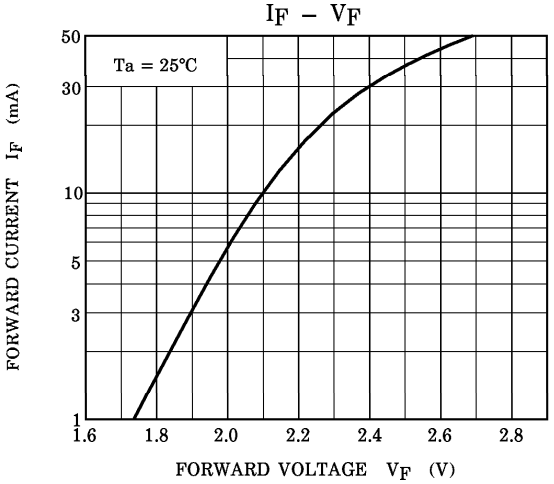
(Note) : Lamps are classified into the following ranks according to their luminous intensity.
Measurement tolerance for each limit is ±15%.
P : 180-360 mcd, Q : 320-640 mcd, R : 560-1120 mcd

PRECAUTION

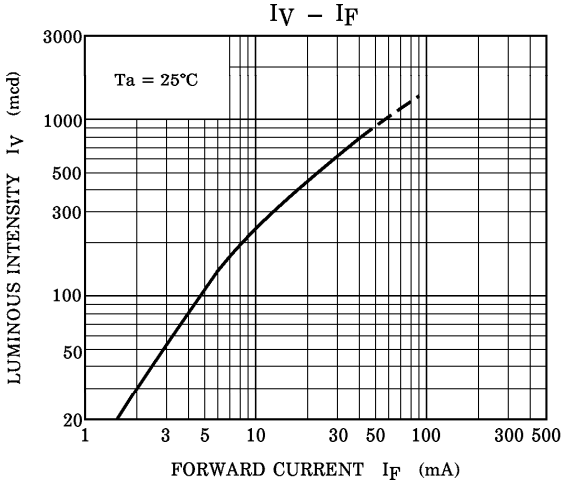
Please be careful of the followings

- Soldering temperature : 260°C max Soldering time : 3 s max
  (Soldering portion of lead : up to 2 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

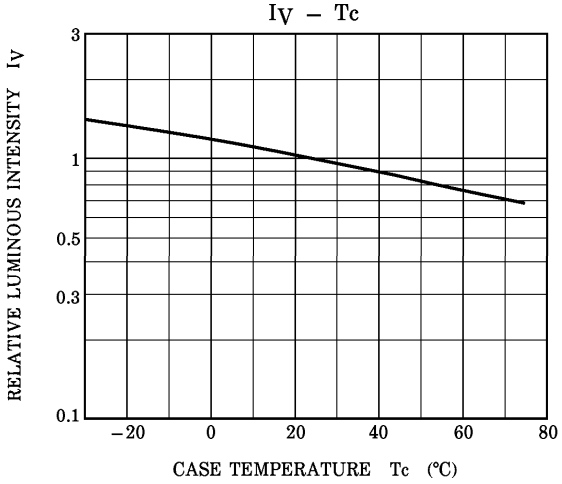
I_F – V_F



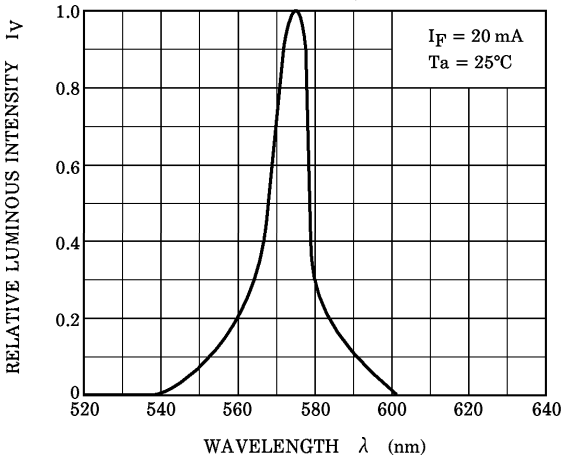
I_V – I_F



I_V – Tc

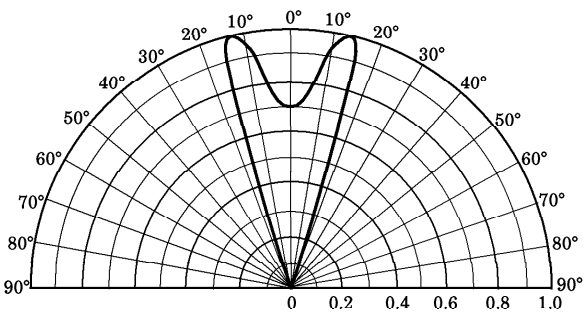


RELATIVE LUMINOUS INTENSITY – WAVELENGTH

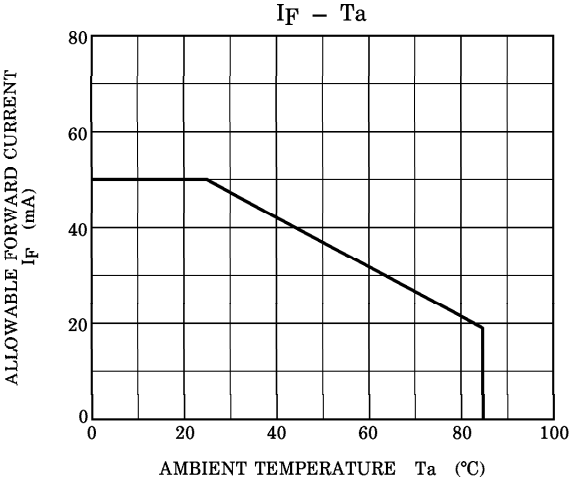


RADIATION PATTERN

Ta = 25°C



I_F – Ta



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